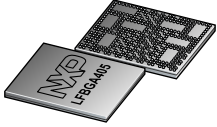


SOT2183-1

FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

2 July 2025

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FCPBGA405
Package style descriptive code	FC-PBGA (flip chip - plastic ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-06-2025
Manufacturer package code	98ASA01934D

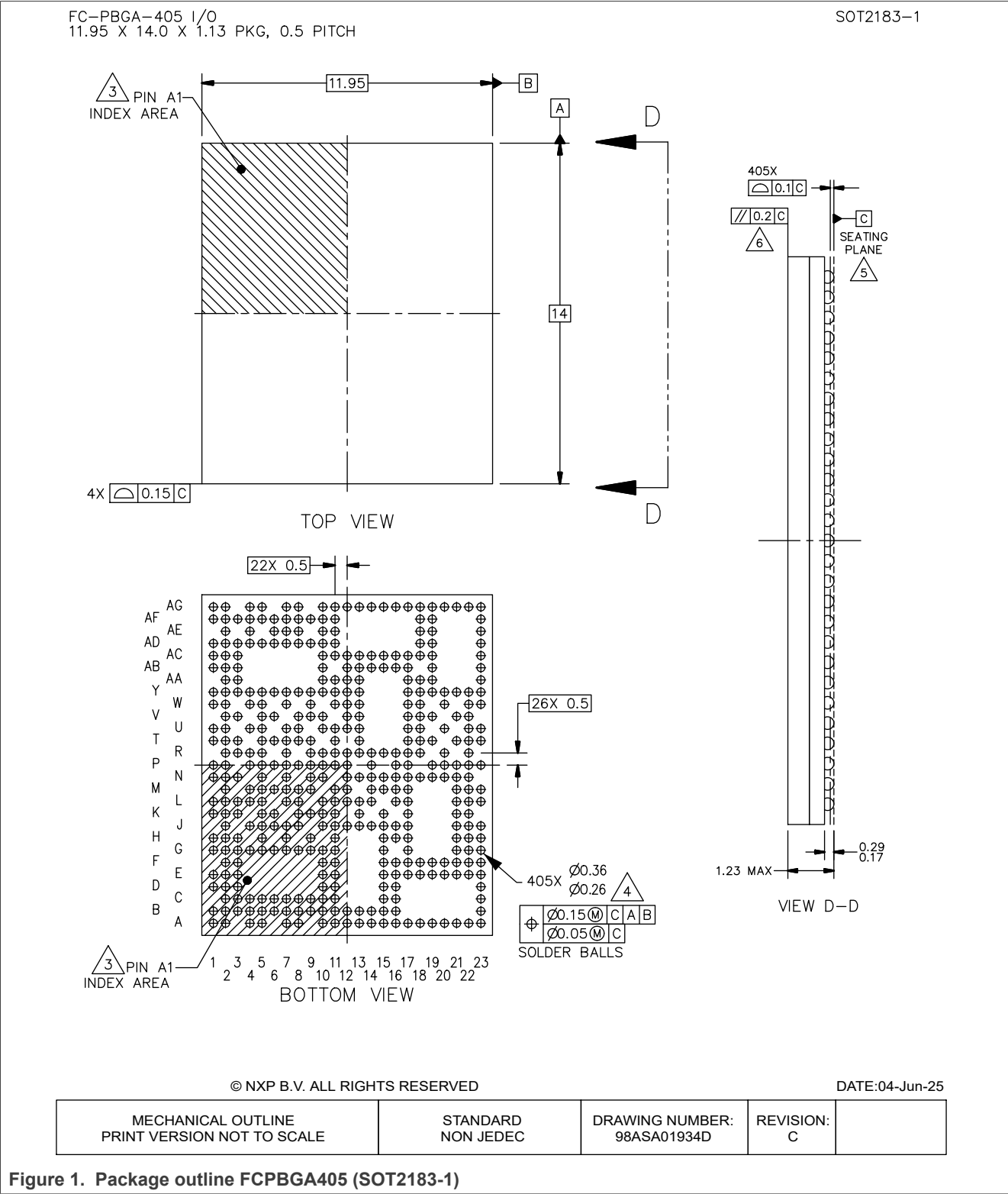
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	13.9	14	14.1	mm
package width	11.85	11.95	12.05	mm
seated height	1.03	1.13	1.23	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	405	-	



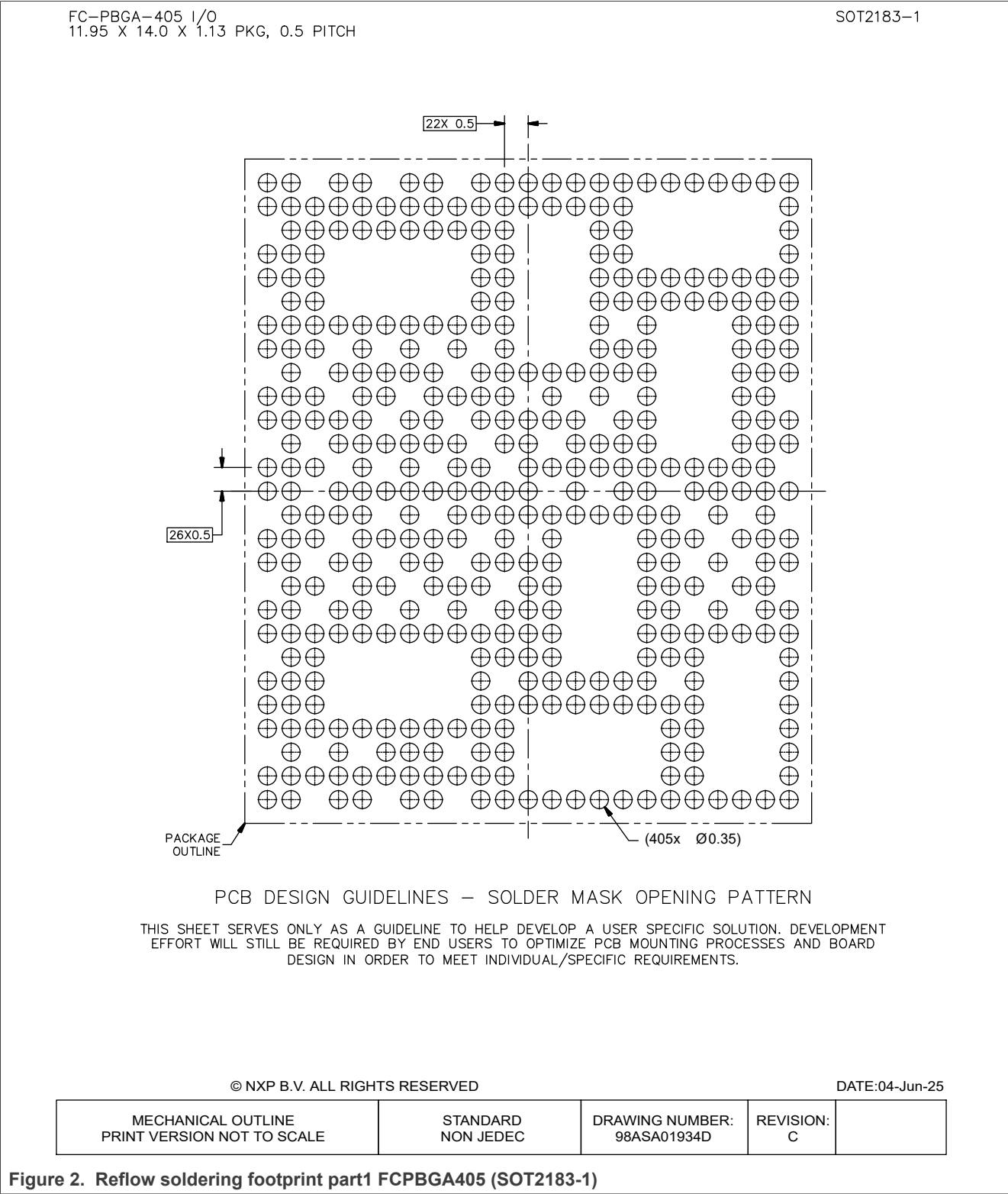
FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

2 Package outline



FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

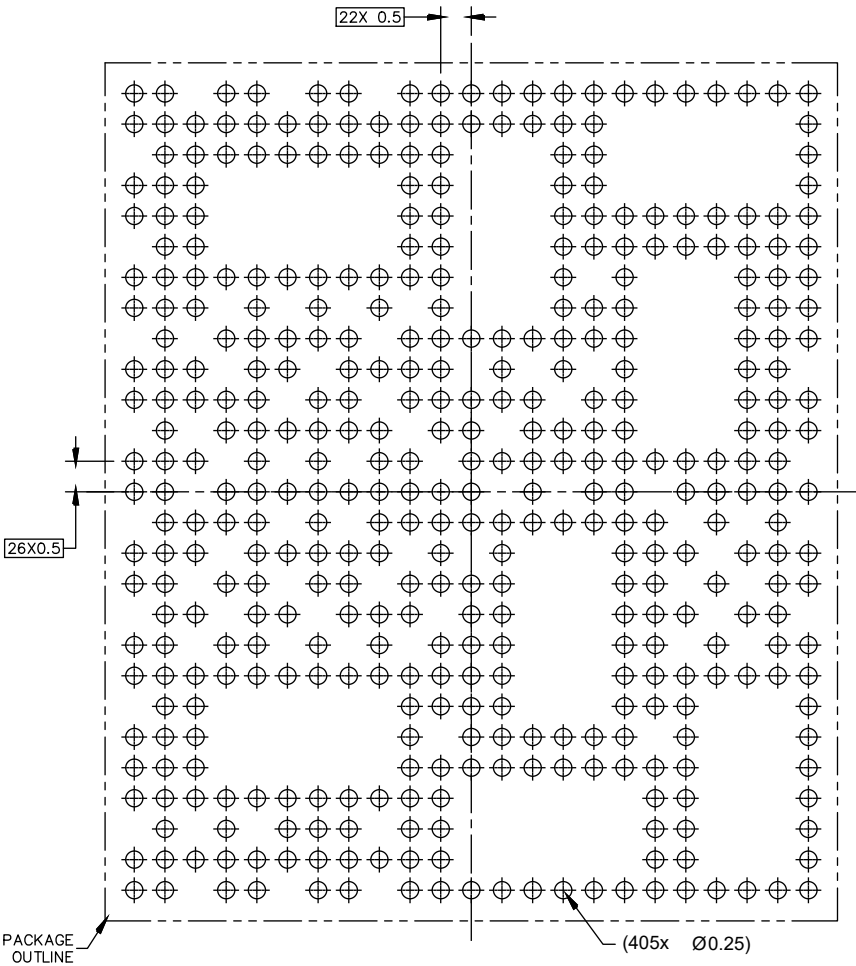
3 Soldering



FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

FC-PBGA-405 I/O
11.95 X 14.0 X 1.13 PKG, 0.5 PITCH

SOT2183-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE:04-Jun-25

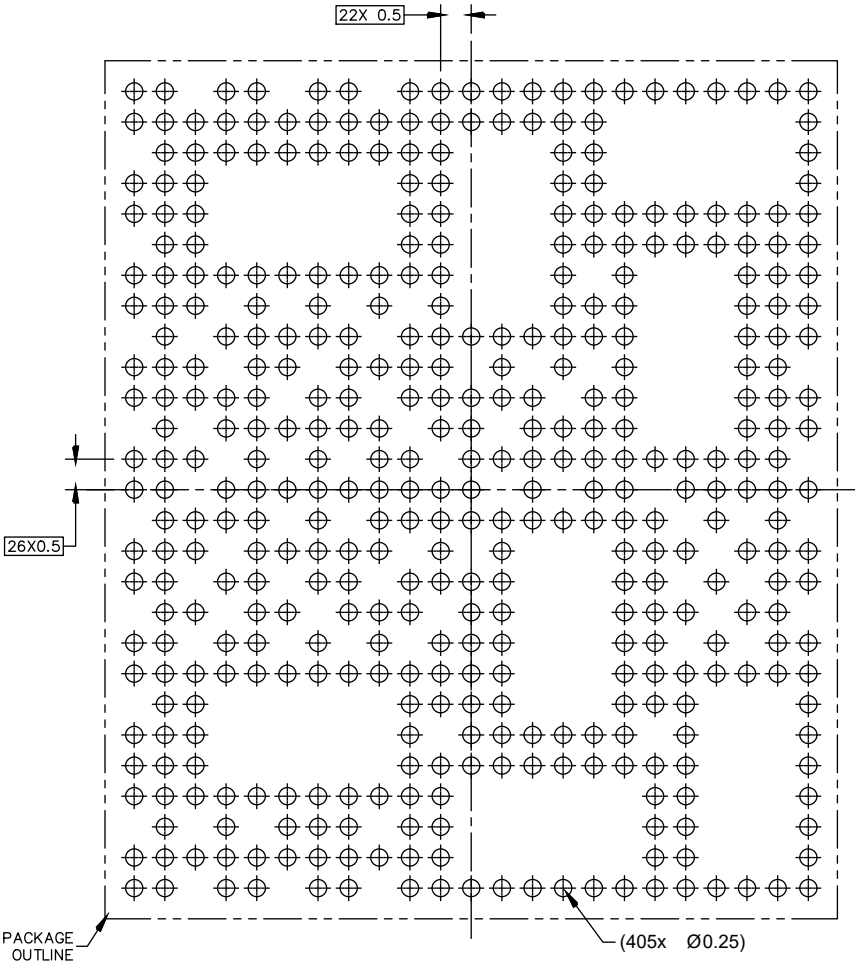
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD NON JEDEC	DRAWING NUMBER: 98ASA01934D	REVISION: C	
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Figure 3. Reflow soldering footprint part2 FCPBGA405 (SOT2183-1)

FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

FC-PBGA-405 I/O
11.95 X 14.0 X 1.13 PKG, 0.5 PITCH

SOT2183-1



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 FCPBGA405 (SOT2183-1)

FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

FC-PBGA-405 I/O
11.95 X 14.0 X 1.13 PKG, 0.5 PITCH

SOT2183-1

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note FCPBGA405 (SOT2183-1)

4 Legal information

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FCPBGA405, flip chip - plastic ball grid array, 405 terminals, 0.5 mm pitch, 14 mm x 11.95 mm x 1.13 mm body

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